

Attorney Docket No. U 013803-1

PATENT

# 6/resp.  
4/16/02  
Jules

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Chien-Ping HUANG

Serial No.: 09/665,818

Group No.: 2814

Filed: September 20, 2000

Examiner: Tran, T.

For: SEMICONDUCTOR PACKAGE FOR ENHANCING HEAT DISSIPATION

**Assistant Commissioner for Patents**  
Washington, D.C. 20231RESPONSE UNDER RULE 1.111

In response to the Official Action dated October 10, 2001 the applicant requests amendment and reconsideration of the above identified application. A substitute specification and claims, and a marked up copy of the specification and claims, are enclosed. A request for a two month extension of time and a Statement under 37 CFR 3.73(b) are also enclosed.

REMARKS

The specification has been amended to conform to United States patent practice and idiomatic English usage, and for the sake of clarity. In particular, the heat sink is recited as "attached to a portion of a surface of at least some leads in the" plurality of leads, as shown in the drawings, rather than "mounted" on or under "the" leads. Recitation of "bonding wires" in all the claims, and of the "upper mold" in the apparatus claims, have been deleted as being

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CERTIFICATE OF MAILING/TRANSMISSION (37 C.F.R. 1.8(a))

I hereby certify that, on the date shown below, this correspondence is being:

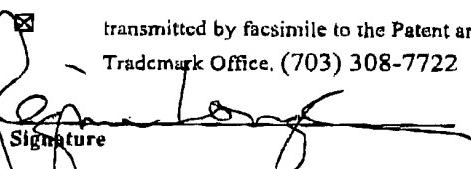
**MAILING**

- deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Date: March 11, 2002**FACSIMILE**

transmitted by facsimile to the Patent and Trademark Office. (703) 308-7722

Signature

  
Regina Ann Loughran

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